## **Document Title**

#### 2Mx16 bit Synchronous Burst Uni-Transistor Random Access Memory

#### **Revision History**

#### Revision No. History

Initial Draft

- Design target

0.0

Draft Date Remark

December 21, 2004 Preliminary

The attached datasheets are provided by SAMSUNG Electronics. SAMSUNG Electronics CO., LTD. reserve the right to change the specifications and products. SAMSUNG Electronics will answer to your questions about device. If you have any questions, please contact the SAMSUNG branch offices.



## 2M x 16 bit Synchronous Burst Uni-Transistor CMOS RAM

#### **FEATURES**

- Process Technology: CMOS
- Organization: 2M x16 bit
- Power Supply Voltage: 1.7~2.0V
- Three State Outputs
- Supports MRS (Mode Register Set)
- MRS control Software Control
- Supports Power Saving modes Deep Power Down mode
- Supports Driver Strength Optimization for system environment
- Supports Async. 4-Page Read / Async. Write Mode
- Supports Sync. Burst Read / Async. Write Mode (Address Latch Type and Low ADV Type)
- Supports Sync. Burst Read / Sync. Burst Write Mode
- Supports 4 word / 8 word / 16 word burst Length
- Supports Linear(Wrap) Burst type
- Latency support : Latency 5 @ 66MHz(tCD 10ns) Latency 4 @ 54MHz(tCD 10ns)
- Supports Burst Read Suspend
- Supports Burst Write Data Masking by /UB & /LB control
- Supports WAIT function to indicate data availability.
- Max. Burst Clock Frequency : 66MHz
- Package Type : 54 FBGA 6.00 x 8.00

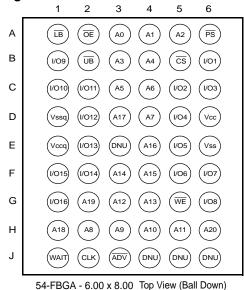
Table 1. PRODUCT FAMILY

#### **GENERAL DESCRIPTION**

The world is moving into the mobile multi-media era and therefore the mobile handsets need much bigger memory capacity to handle the multi-media data. SAMSUNG's UtRAM products are designed to meet all the request from the various customers who want to cope with the fast growing mobile market. UtRAM is the perfect solution for the mobile market with its low cost, high density and high performance feature. K1B3216B7D is fabricated by SAMSUNG's advanced CMOS technology using one transistor memory cell. This device supports the traditional SRAM like asynchronous bus operation (asynchronous page read and asynchronous write), the NOR flash like synchronous bus operation (synchronous burst read and asynchronous write) and the fully synchronous bus operation (synchronous burst read and synchronous burst write). These three bus operation modes are defined through the mode register setting. The optimization of output driver strength is possible through the mode register setting to adjust for the different data loadings. Through this driver strength optimization, the device can minimize the noise generated on the data bus during read operation. This device also supports DPD(Deep Power Down) mode in which it is possible to achive very low power consumption.

				A	Power Di			
Product Family	Operating Temp.	Vcc Range	Clock Freq. (Max)	Async. Speed (tAA)	Standby (Isв1, Max.)	Operating (Icc2, Max.)	PKG Type	
K1B3216B7D-I	Industrial(-40~85°C)	1.7~2.0V	66MHz	70ns	100uA	35mA	54 FBGA 6.00 x 8.00	

#### Fig.1 PIN DESCRIPTION



#### Table 2. PIN DESCRIPTION

Name	Function	Name	Function
CLK	Clock Input	Vcc	Power Supply
ADV	Address Input Valid	Vccq	I/O Power Supply
PS	Power Save	Vss	Ground
CS	Chip Select	Vssq	I/O Ground
OE	Output Enable Input	UB	Upper Byte(I/O9~16)
WE	Write Enable Input	LB	Lower Byte(I/O1~8)
A0~A20	Address Inputs	WAIT	Data Availability
I/O1~I/O16	Data Inputs/Outputs	DNU	Do Not Use

SAMSUNG ELECTRONICS CO., LTD. reserves the right to change products and specifications without notice.



# http://www.BDTIC.com/SAMSUNG Preliminary UtRAM

Page

## CONTENTS

Revision History	1
Features and General Description	· · 2
Power Up Sequence	
Functional Description	8
Mode Register Setting Operation	10
Mode Register Setting Timing	11
Asynchronous Operation	12
Asynchronous 4 Page Read Operation	12
Asynchronous Write Operation	12
Asynchronous Write Operation in Synchronous Mode	12
Synchronous Burst Operation	12
Synchronous Burst Read Operation	12
Synchronous Burst Write Operation	12
Synchronous Burst Operation Terminology	13
Clock	13
Latency Count	13
Burst Length	13
Burst Stop	
WAIT Control	14
Burst Type ·	14
Low Power Feature	15
Product List	
Absolute Maximum Ratings	16
Recommended DC Operating Conditions	16
Capacitance	16
DC and Operating Characteristics	- 16
Asynchronous AC Characteristics	17
Asynchronous Timing Waveforms	18
Synchronous AC Characteristics	- •27
Synchronous Timing Waveforms	28
Transition Timing Waveforms	37
Package Dimension	43



# http://www.BDTIC.com/SAMSUNG Preliminary UtRAM

#### LIST of TABLES

#### Page

Table 1.	Product Family	2
Table 2.	Pin Description	2
Table 3.	Asynchronous 4 Page Read & Asynchronous Write Mode Truth Table	8
Table 4.	Synchronous Burst Read & Asynchronous Write Mode Truth Table	8
Table 5.	Synchronous Burst Read & Synchronous Burst Write Mode Truth Table	9
Table 6.	Mode Register Setting according to Field of Function	10
Table 7.	Mode Register Set.	10
Table 8.	Latency Count Support	13
Table 9.	Number of Clocks for 1st Data	13
	Burst Sequence	
	Product List	
Table 12.	Absolute Maximum Ratings	16
Table 13.	Recommended DC Operating Conditions	16
Table 14.	Capacitance	16
Table 15.	DC and Operating Characteristics	16
Table 16.	Asynchronous AC Characteristics	17
Table 17.	Asynchronous Read AC Characteristics	18
Table 18.	Asynchronous Page Read AC Characteristics	19
Table 19.	Asynchronous Write AC Characteristics(WE Controlled)	20
	Asynchronous Write AC Characteristics(UB & LB Controlled)	
	Asynch. Write in Synch. Mode AC Characteristics(Address Latch Type, WE Controlled)	
	Asynch. Write in Synch. Mode AC Characteristics(Address Latch Type, UB & LB Controlled)	
Table 23.	Asynch. Write in Synch. Mode AC Characteristics(Low ADV Type, WE Controlled)	24
Table 24.	Asynch. Write in Synch. Mode AC Characteristics(Low ADV Type, UB & LB Controlled)	- 25
Table 25.	Asynch. Write in Synch. Mode AC Characteristics(Low ADV Type Multiple Write, WE Controlled)	- 26
Table 26.	Synchronous AC Characteristics	- 27
Table 27.	Burst Operation AC Characteristics	- 28
Table 28.	Burst Read AC Characteristics(CS Toggling Consecutive Burst)	. 29
	Burst Read AC Characteristics(CS Low Holding Consecutive Burst)	
Table 30.	Burst Read AC Characteristics(Last Data Sustaining)	31
Table 31.	Burst Write AC Characteristics(CS Toggling Consecutive Burst)	- 32
Table 32.	Burst Write AC Characteristics(CS Low Holding Consecutive Burst)	33
Table 33.	Burst Read Stop AC Characteristics	34
Table 34.	Burst Write Stop AC Characteristics	- 34
Table 35.	Burst Read Suspend AC Characteristics	- 36
Table 36.	Burst Read to Asynch. Write(Address Latch Type) AC Characteristics	37
Table 37.	Burst Read to Asynch. Write(Low ADV Type) AC Characteristics	- 38
Table 38.	Asynch. Write(Address Latch Type) to Burst Read AC Characteristics	39
Table 39.	Asynch. Write(Low ADV Type) to Burst Read AC Characteristics	40
Table 40.	Burst Read to Burst Write AC Characteristics	41
Table 41.	Burst Write to Burst Read AC Characteristics	42



# http://www.BDTIC.com/SAMSUNG *Preliminary* U*t*RAM

#### LIST of FIGURES

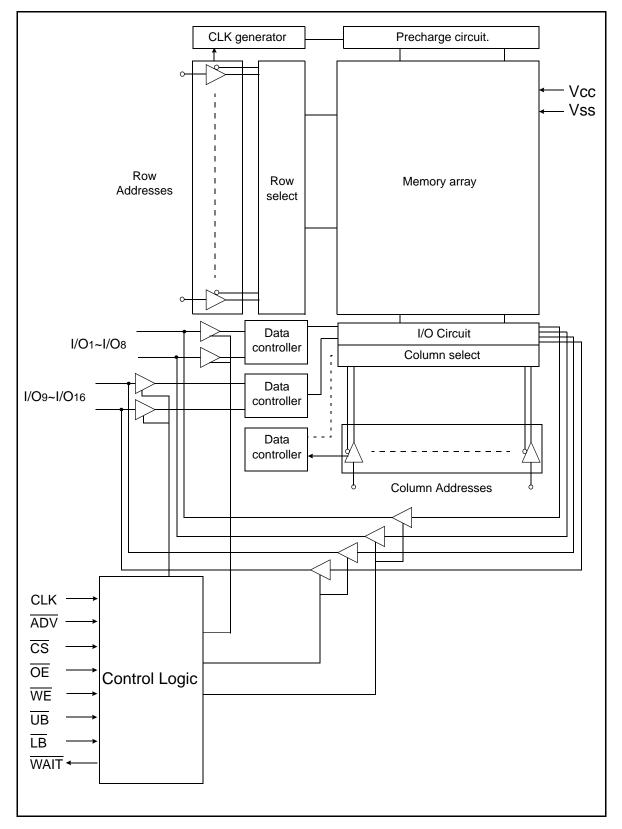
#### Page

	Pin Description	
Figure 2.		6
Figure 3.	Power Up Timing	7
Figure 4.	Standby Mode State Machine	7
Figure 5.	Mode Register Setting Timing	11
Figure 6.	Asynchronous 4-Page Read	12
Figure 7.	Asynchronous Write	12
Figure 8.	Synchronous Burst Read	12
Figure 9.	Synchronous Burst Write	12
Figure 10.	Latency Configuration(Read)	13
Figure 11.	WAIT Control and Read/Write Latency Control	14
Figure 12.	AC Output Load Circuit(Asynchronous)	17
Figure 13.	. Timing Waveform of Asynchronous Read Cycle.	18
Figure 14.	. Timing Waveform of Page Read Cycle	29
Figure 15.	. Timing Waveform of Write Cycle(Asynchronous, WE Controlled)	20
Figure 16.	. Timing Waveform of Write Cycle(Asynchronous, UB & LB Controlled)	21
	. Timing Waveform of Write Cycle(Asynchronous, Address Latch Type, WE Controlled) 2	
	. Timing Waveform of Write Cycle(Asynchronous, Addr <u>ess Latch Type</u> , UB & LB Controlled) 2	
	. Timing Waveform of Write Cycle(Asynchronous, Low <u>ADV</u> Type, <u>WE</u> Controlled).	
	. Timing Waveform of Write Cycle(Asynchronous, Low ADV Type, UB & LB Controlled) 2	
	. Timing Waveform of Multiple Write Cycle(Asynchronous, Low ADV Type, WE Controlled.)	
	. AC Output Load Circuit(Synchronous)	
	. Timing Waveform of Basic Burst Operation	
	. Timing Waveform of Burst Read Cycle(CS Toggling Consecutive Burst Read)	
	. Timing Waveform of Burst Read Cycle(CS Low Holding Consecutive Burst Read).	
	. Timing Waveform of Burst Read Cycle(Last Data Sustaining)	
	. Timing Waveform of Burst Write Cycle( <u>CS</u> Toggling Consecutive Burst Write)	
	. Timing Waveform of Burst Write Cycle(CS Low Holding Consecutive Burst Write).	
	. Timing Waveform of Burst Read Stop by <u>CS</u>	
	. Timing Waveform of Burst Write Stop by $\overline{CS}$	
	. Timing Waveform of Burst Read Suspend Cycle	
	. Synch. Burst Read to Asynch. Write(Addr <u>ess L</u> atch Type) Timing Waveform	
	. Synch. Burst Read to Asynch. Write(Low ADV Type) Timing Waveform.	
	Asynch. Write(Address Latch Type) to Synch. Burst Read Timing Waveform	
	. Asynch. Write(Low ADV Type) to Synch. Burst Read Timing Waveform	
	. Synch. Burst Read to Synch. Burst Write Timing Waveform	
Figure 37.	. Synch. Burst Write to Synch. Burst Read Timing Waveform	42



# http://www.BDTIC.com/SAMSUNG Preliminary UtRAM

#### Fig.2 FUNCTIONAL BLOCK DIAGRAM





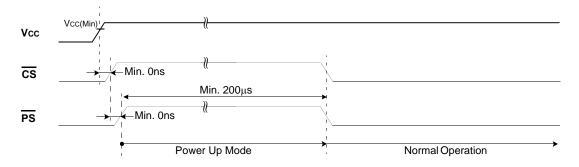
#### POWER UP SEQUENCE

After applying Vcc upto minimum operating voltage(1.7V), drive  $\overline{CS}$  High. Then the device gets into the Power Up mode. Wait for minimum 200 $\mu$ s to get into the normal operation mode. During the Power Up mode, the standby current can not be guaranteed. To get the stable standby current level, at least one cycle of active operation should be implemented regardless of wait time duration. To get the appropriate device operation, be sure to keep the following power up sequence.

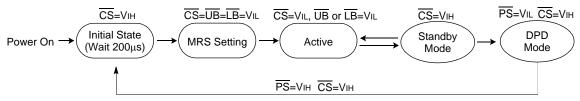
1. Apply power.

2. Maintain stable power(Vcc min.=1.7V) for a minimum  $200\mu s$  with  $\overline{CS} \& \overline{PS}$  high.

#### Fig.3 POWER UP TIMING



#### Fig.4 STANDBY MODE STATE MACHINES



Default mode after power up is Asynchronous mode (4 Page Read and Asynchronous Write). But this default mode is not 100% guaranteed so MRS setting sequence is highly recommended after power up.



#### FUNCTIONAL DESCRIPTION

#### Table 3. ASYNCHRONOUS 4 PAGE READ & ASYNCHRONOUS WRITE MODE (A15/A14=0/0)

CS	OE	WE	LB	UB	<b>I/O</b> 0~7	<b>I/O</b> 8~15	Mode	Power
н	X <sup>1)</sup>	X <sup>1)</sup>	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z	Deselected	Standby
L	н	н	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z	Output Disabled	Active
L	X <sup>1)</sup>	X <sup>1)</sup>	н	н	High-Z	High-Z	Output Disabled	Active
L	L	Н	L	н	Dout	High-Z	Lower Byte Read	Active
L	L	Н	н	L	High-Z	Dout	Upper Byte Read	Active
L	L	Н	L	L	Dout	Dout	Word Read	Active
L	н	L	L	н	Din	High-Z	Lower Byte Write	Active
L	Н	L	Н	L	High-Z	Din	Upper Byte Write	Active
L	Н	L	L	L L Din		Din	Word Write	Active

1. X must be VIL or VIH.

2. In asynchronous mode, Clock and ADV are ignored.

3. /WAIT pin is High-Z in Asynchronous mode.

#### Table 4. SYNCHRONOUS BURST READ & ASYNCHRONOUS WRITE MODE(A15/A14=0/1)

CS	OE	WE	LB	UB	<b>I/O</b> 0~7	<b>I/O</b> 8~15	CLK	ADV	Mode	Power
н	X <sup>1)</sup>	X <sup>1)</sup>	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z	X <sup>1)</sup>	X <sup>1)</sup>	Deselected	Standby
L	н	н	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z	X <sup>1)</sup>	н	Output Disabled	Active
L	X <sup>1)</sup>	X <sup>1)</sup>	н	н	High-Z	High-Z	X <sup>1)</sup>	н	Output Disabled	Active
L	X <sup>1)</sup>	н	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z			Read Command	Active
L	L	н	L	Н	Dout	High-Z		Н	Lower Byte Read	Active
L	L	н	н	L	High-Z	Dout		н	Upper Byte Read	Active
L	L	н	L	L	Dout	Dout		н	Word Read	Active
L	н	L	L	Н	Din	High-Z	X <sup>1)</sup>	⁻∟ or ՆՐ	Lower Byte Write	Active
L	н	L	Н	L	High-Z	Din	X <sup>1)</sup>	□_ or ጌ_	Upper Byte Write	Active
L	н	L	L	L	Din	Din	X <sup>1)</sup>	⁻∟ or ЪГ	Word Write	Active

1. X must be VIL or VIH.

2. /WAIT is device output signal so does not have any affect to the mode definition. Please refer to each timing diagram for /WAIT pin function.



CS	OE	WE	LB	UB	<b>I/O</b> 0~7	<b>I/O</b> 8~15	CLK	ADV	Mode	Power
н	X <sup>1)</sup>	X <sup>1)</sup>	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z	X <sup>1)</sup>	X <sup>1)</sup>	Deselected	Standby
L	н	н	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z	X <sup>1)</sup>	Н	Output Disabled	Active
L	X <sup>1)</sup>	X <sup>1)</sup>	Н	н	High-Z	High-Z	X <sup>1)</sup>	н	Output Disabled	Active
L	X <sup>1)</sup>	Н	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z			Read Command	Active
L	L	н	L	н	Dout	High-Z		н	Lower Byte Read	Active
L	L	Н	Н	L	High-Z	Dout		Н	Upper Byte Read	Active
L	L	н	L	L	Dout	Dout	5	Н	Word Read	Active
L	X <sup>1)</sup>	LorЪ	X <sup>1)</sup>	X <sup>1)</sup>	High-Z	High-Z			Write Command	Active
L	Н	X <sup>1)</sup>	L	Н	Din	High-Z		Н	Lower Byte Write	Active
L	н	X <sup>1)</sup>	Н	L	High-Z	Din		Н	Upper Byte Write	Active
L	Н	X <sup>1)</sup>	L	L	Din	Din		Н	Word Write	Active

#### Table 5. SYNCHRONOUS BURST READ & SYNCHRONOUS WRITE MODE(A15/A14=1/0)

1. X must be VIL or VIH.

3. /WAIT is device output signal so does not have any affect to the mode definition. Please refer to each timing diagram for /WAIT pin function.

4. The last data written in the previous Asynchronous write mode is not valid. To make the lastly written data valid, then implement at least one dummy write cycle before change mode into synchronous burst read and synchronous burst write mode.

5. The data written in Synchronous burst write operation can be corrupted by the next Asynchronous write operation. So the transition from Synchronous burst write operation to Asynchronous write operation is prohibited.



#### MODE REGISTER SETTING OPERATION

The device has several modes : Asynchronous Page Read mode, Asynchronous Write mode, Synchronous Burst Read mode, Synchronous Burst Write mode, Standby mode. Mode Register Set(MRS) option also defines Burst Length, Burst Type, Wait Polarity and Latency Count at Synchronous Burst Read/Write mode.

#### Mode Register Set (MRS)

The mode register stores the data for controlling the various operation modes of UtRAM. It programs Burst Length, Burst Type, Latency Count and various vendor specific options to make UtRAM useful for a variety of different applications. The default values of mode register are defined, therefore when the reserved address is input, the device runs at default modes. The mode register is written by driving CS, ADV, WE, UB, LB to VIL and OE to VIH during valid address. The mode register is divided into various fields depending on the fields of functions. Deep Power Down uses A4, Burst Length field uses A5~A7, Burst Type uses A8, Latency Count uses A9~A11, Wait Polarity uses A13, Operation Mode uses A14~A15 and Driver Strength uses A16~A17.

Refer to the Table below for detailed Mode Register Setting. A18~A22 addresses are "Don't care" in Mode Register Setting.

#### Table 6. Mode Register Setting according to field of function

Address	A17~A16	A15~A14	A13	A12	A11~A9	A8	A7~A5	A4	A3~A0
Function	DS	MS	WP	RFU	Latency	BT	BL	DPD	RFU

NOTE : DS(Driver Strength), MS(Mode Select), WP(Wait Polarity), Latency(Latency Count), BT(Burst Type), BL(Burst Length), DPD(Deep Power Down), RFU(Reserved for Future Use)

#### Table 7. Mode Register Set

	Drive	r Strengt	h		Mode Select							WAIT Polarity			
A17	A16	I	DS	A	15	A14	MS					3	WP		
0	0	Full	Drive		0	0 As	sync. 4	Page Read /	Async. '	Write	0		Low Enable		
0	1	1/2	Drive		0	1 :	Sync. Burst Read / Async. Write						High Enable		
1	0	1/4	Drive		1	0 Sy	nc. Bur	st Read / Syn	c. Burst	Write					
	RFU			Laten	tency Count			Burst Type Bur			Burst Le	ength	Dee	p Power Down	
A12	R	FU	A11	A10	A9	Latency	A8	вт	A7	A6	A5	BL	A4	DPD	
0	м	ust	0	0	0	3	0	Linear	0	1	0	4 word	0	DPD Enable	
1 DNU*		NU*	0	0	1	4	1	DNU*	0	1	1	8 word	1	DPD Disable	
			0	1	0	5			1	0	0	16 word			

\* DNU: Do Not Use.

NOTE :

\* The address bits other than those listed in the table above are reserved.

1

6

For example, Burst Length address bits(A7:A6:A5) have 4 sets of reserved bits like 0:0:0, 0:0:1, 1:0:1 and 1:1:0.

If the reserved address bits are input, then the mode will be set into the default mode. Each field has its own default mode and these default modes are written in blue-bold in the table above.

1

1

DNU\*

\* A12 is a reserved bit for future use. A12 must be set as "0".

1

0

\* Not all the mode settings are tested. Per the mode settings to be tested.

\* The last data written in the previous Asynchronous write mode is not valid. To make the lastly written data valid, then implement at least one dummy write cycle before change mode into synchronous burst read and synchronous burst write mode.

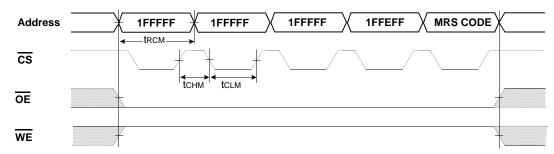
\* The data written in Synchronous burst write operation can be corrupted by the next Asynchronous write operation. So the transition from Synchronous burst write operation to Asynchronous write operation is prohibited.



#### MODE REGISTER SETTING TIMING

This device supports software access control type mode register setting timing. This timing consists of 5 cycles of Read operation. Each cycle of Read Operation is normal asynchronous read operation. Clock and ADV are don't care and WAIT signal is High-Z. CS should be toggling between cycles. The address for 1st, 2nd and 3rd cycle should be 1FFFFF(h) and the address for 4th cycle should be 1FFEFF. The address for 5th cycle should be MRS code(Register setting values).

MRS TIMING WAVEFORM(Clock, ADV, UB, LB are Don't care, WAIT=High-Z)



#### AC CHARACTERISTICS

Parameter	Sym-	Min	Max	Unit	Parameter	Sym-	Mi	Ма	Unit
Read Cycle time	<b>t</b> RCM	70	-	ns	CS Low pulse width	<b>t</b> CLM	60	-	ns
CS High pulse width	tснм	10	-	ns					



#### **ASYNCHRONOUS OPERATION**

#### **Asynchronous 4 Page Read Operation**

Asynchronous normal read operation starts when  $\overline{CS}$ ,  $\overline{OE}$  and  $\overline{UB}$  or  $\overline{LB}$  are driven to VIL under the valid address without toggling page addresses(A0, A1). If the page addresses(A0, A1) are toggled under the other valid address, the first data will be out with the normal read cycle time(tRC) and the second, the third and the fourth data will be out with the page cycle time(tPC). ( $\overline{WE}$  should be driven to VIH during the asynchronous (page) read operation)

Clock, ADV, WAIT signals are ignored during the asynchronous (page) read operation.

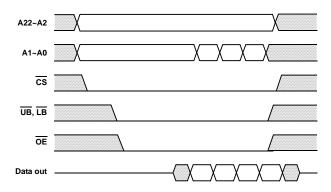
#### **Asynchronous Write Operation**

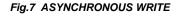
Asynchronous write operation starts when  $\overline{CS}$ ,  $\overline{WE}$  and  $\overline{UB}$  or  $\overline{LB}$  are driven to VIL under the valid address.( $\overline{OE}$  should be driven to VIH during the asynchronous write operation.) Clock, ADV, WAIT signals are ignored during the asynchronous (page) read operation.

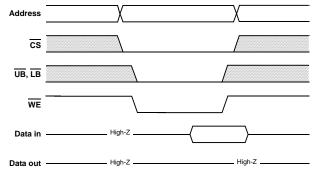
#### Asynchronous Write Operation in Synchronous Mode

A write operation starts when  $\overline{CS}$ ,  $\overline{WE}$  and  $\overline{UB}$  or  $\overline{LB}$  are driven to  $V_{IL}$  under the valid address. Clock input does not have any affect to the write operation ( $\overline{OE}$  should be driven to  $V_{IH}$  during write operation.  $\overline{ADV}$  can be either toggling for address latch or held in  $V_{IL}$ ). Clock,  $\overline{ADV}$ ,  $\overline{WAIT}$  signals are ignored during the asynchronous (page) read operation.

#### Fig.6 ASYNCHRONOUS 4-PAGE READ







#### SYNCHRONOUS BURST OPERATION

Burst mode operations enable the system to get high performance read and write operation. The address to be accessed is latched on the rising edge of clock or ADV (whichever occurs first). CS should be setup before the address latch. During this first clock rising edge, WE indicates whether the operation is going to be a Read(WE High) or a Write(WE Low). For the optimized Burst Mode to each system, the system should determine how many clock cycles are required for the first data of each burst access(Latency Count), how many words the device outputs at an access(Burst Length) and which type of burst operation(Burst Type : Linear ) is needed. The Wait Polarity should also be determined.(See Table "Mode Register Set")

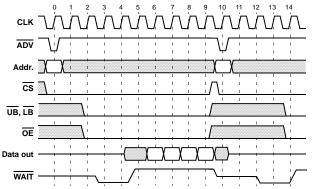
#### Synchronous Burst Read Operation

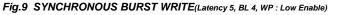
The Synchronous Burst Read command is implemented when the clock rising is detected during the  $\overline{\text{ADV}}$  low pulse.  $\overline{\text{ADV}}$  and  $\overline{\text{CS}}$  should be set up before the clock rising. During Read command,  $\overline{\text{WE}}$  should be held in VIH. The multiple clock risings(during low  $\overline{\text{ADV}}$  period) are allowed but the burst operation starts from the first clock rising. The first data will be out with Latency count and tCD.

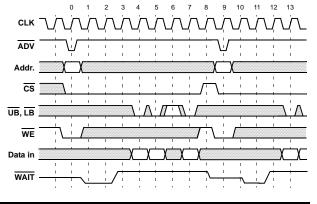
#### **Synchronous Burst Write Operation**

The Synchronous Burst Write command is implemented when the clock rising is detected during the ADV and WE low pulse. ADV, WE and CS should be set up before the clock rising. The multiple clock risings(during low ADV period) are allowed but the burst operation starts from the first clock rising. The first data will be written in the Latency clock with tDS.

#### Fig.8 SYNCHRONOUS BURST READ(Latency 5, BL 4, WP : Low Enable)









#### SYNCHRONOUS BURST OPERATION TERMINOLOGY

#### Clock(CLK)

The clock input is used as the reference for synchronous burst read and write operation of UtRAM. The synchronous burst read and write operation is synchronized to the rising edge of the clock. The clock transitions must swing between VIL and VIH.

#### Latency Count

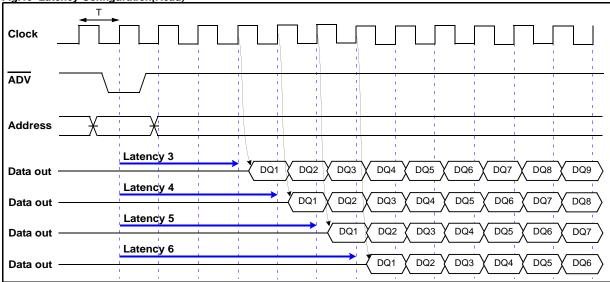
The Latency Count configuration tells the device how many clocks must elapse from the burst command before the first data should be available on its data pins. This value depends on the input clock frequency. The supported Latency Count is as follows.

#### Table 8. Latency Count support : 3, 4, 5

Clock Frequency	Upto 66MHz	Upto 54MHz	Upto 40MHz		
Latency Count	5	4	3		

Table 9. Number of Clocks for 1st Data

Set Latency	Latency 3	Latency 4	Latency 5
# of Clocks for 1st data(Read)	4	5	6
# of Clocks for 1st data(Write)	2	3	4



#### Fig.10 Latency Configuration(Read)

NOTE : The first data will always keep the Latency. From the second data, some period of wait time might be caused by WAIT pin.

#### **Burst Length**

Burst Length identifies how many data the device outputs at an access. The device supports 4 word, 8 word and 16 word burst read or write. The first data will be out with the set Latency + tCD. From the second data, the data will be out with tCD from each clock.

#### Burst Stop

Burst stop is used when the system wants to stop burst operation on special purpose. If driving  $\overline{CS}$  to VIH during the burst read operation, then the burst operation will be stopped. During the burst read operation, the new burst operation can not be issued. The new burst operation can be issued only after the previous burst operation is finished.

The burst stop feature is very useful because it enables the user to utilize the un-supported burst length such as 1 burst or 2 burst which accounts for big portion in usage for the mobile handset application environment.

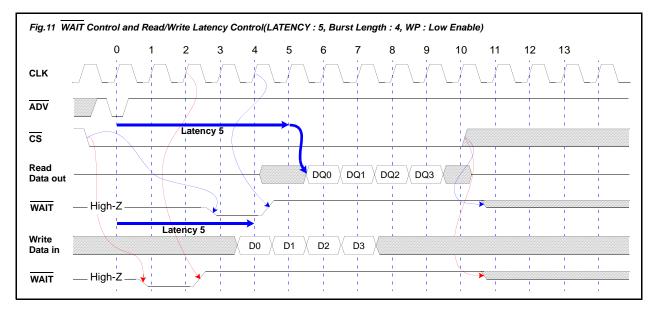


#### SYNCHRONOUS BURST OPERATION TERMINOLOGY

#### WAIT Control(WAIT)

The WAIT signal is the device's output signal which indicates to the host system when the device's data-out or data-in is valid. To be compatible with the Flash interfaces of various microprocessor types, the WAIT polarity(WP) can be configured. The polarity can be programmed to be either low enable or high enable.

For the timing of WAIT signal, the WAIT signal should be set active one clock prior to the data regardless of Read or Write cycle.



#### **Burst Type**

The device supports Linear type burst sequence. Linear type burst sequentially increments the burst address from the starting address. The detailed Linear type burst address sequence is shown in burst sequence table.

Start		Burst Address Sequence(D	Decimal)
Length	4 word Burst	8 word Burst	16 word Burst
0	0-1-2-3	0-1-2-3-4-5-6-7	0-1-2-3-4-5-6-7-8-9-10-11-12-13-14-15
1	1-2-3-0	1-2-3-4-5-6-7-0	1-2-3-4-5-6-7-8-9-10-11-12-13-14-15-0
2	2-3-0-1	2-3-4-5-6-7-0-1	2-3-4-5-6-7-8-9-10-11-12-13-14-15-0-1
3	3-0-1-2	3-4-5-6-7-0-1-2	3-4-5-6-7-8-9-10-11-12-13-14-15-0-1-2
4		4-5-6-7-0-1-2-3	4-5-6-7-8-9-10-11-12-13-14-15-0-1-2-3
5		5-6-7-0-1-2-3-4	5-6-7-8-9-10-11-12-13-14-15-0-1-2-3-4
6		6-7-0-1-2-3-4-5	6-7-8-9-10-11-12-13-14-15-0-1-2-3-4-5
7		7-0-1-2-3-4-5-6	7-8-9-10-11-12-13-14-15-0-1-2-3-4-5-6
~			~
14			14-15-0-1-2-3-4-5-6-7-8-9-10-11-12-13
15			15-0-1-2-3-4-5-6-7-8-9-10-11-12-13-14

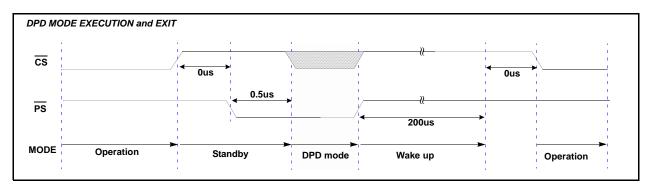
#### Table 10. Burst Sequence



#### LOW POWER FEATURES

#### Deep Power Down(DPD) mode

The deep power down mode disables all refresh related activity. This mode is used when the system does not need to store the data in UtRAM. The data stored in UtRAM will become corrupted if DPD mode is executed. The default mode is DPD enabled. But even though DPD mode is enabled through the Mode Register Setting, DPD mode execution is still needed to disable all the refresh related activity. So the normal operation can be executed in DPD enabled mode as long as MRS pin is not driven to low for over 0.5µs. Wake up sequence is needed for the device to exit from the DPD executed mode. Once the device gets out of DPD executed mode, the Mode Register Settings are initialized into the default mode so the mode register should be re-written for a proper operation.





#### Table 11. PRODUCT LIST

Industrial Temperature Products (-40~85°C)		
Part Name	Function	
K1B3216B7D	1.8V, 70ns, 66MHz, DPD	

#### Table 12. ABSOLUTE MAXIMUM RATINGS<sup>1)</sup>

Item	Symbol	Ratings	Unit
Voltage on any pin relative to Vss	Vin, Vout	-0.2 to Vcc+0.3V	V
Power supply voltage relative to Vss	Vcc	-0.2 to 2.5V	V
Power Dissipation	PD	1.0	W
Storage temperature	Тѕтс	-65 to 150	°C
Operating Temperature	Та	-40 to 85	°C

1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation should be restricted to be used under recommended operating condition. Exposure to absolute maximum rating conditions longer than 1 second may affect reliability.

#### Table 13. RECOMMENDED DC OPERATING CONDITIONS<sup>1)</sup>

Item	Symbol	Min	Тур	Max	Unit
Power supply voltage	Vcc	1.7	1.85	2.0	V
Ground	Vss	0	0	0	V
Input high voltage	Vін	0.8 x Vcc	-	Vcc+0.22)	V
Input low voltage	VIL	-0.2 <sup>3)</sup>	-	0.3	V

1. TA=-40 to 85°C, otherwise specified.

2. Overshoot: Vcc+1.0V in case of pulse width ≤3ns.

3. Undershoot: -1.0V in case of pulse width ≤3ns.

4. Overshoot and undershoot are sampled, not 100% tested.

#### Table 14. CAPACITANCE<sup>1)</sup>(f=1MHz, TA=25°C)

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	CIN	VIN=0V	-	8	pF
Input/Output capacitance	Сю	VIO=0V	-	10	pF

1. Capacitance is sampled, not 100% tested.

#### Table 15. DC AND OPERATING CHARACTERISTICS

Item	Symbol	Test Conditions	Min	Тур	Max	Unit
Input Leakage Current	L	VIN=Vss to Vcc	-1	-	1	μA
Output Leakage Current	Ilo	$\overline{CS}$ =VIH, $\overline{OE}$ =VIH or $\overline{WE}$ =VIL, VIO=Vss to VCC	-1	-	1	μA
Average Operating Current	ICC2	Cycle time=tRC+3tPC, IIO=0mA, 100% duty, $\overline{CS}$ =VIL, VIN=VIL or VIH	-	-	35	mA
Output Low Voltage	Vol	IoL=0.1mA	-	-	0.2	V
Output High Voltage	Vон	Іон=-0.1mA	1.4	-	-	V
Standby Current(CMOS)	ISB1 <sup>1)</sup>	CS≥Vcc-0.2V, Other inputs=Vss to Vcc	-	-	100	μΑ
DPD(Deep Power Down)	ISBD	PS≤0.2V, Other inputs=Vss to Vcc	-	-	20	μΑ

1. Standby mode is supposed to be set up after at least one active operation. ISB1 is measured after 60ms from the time when standby mode is set up.

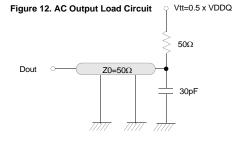


# http://www.BDTIC.com/SAMSUNG Preliminary

# K1B3216B7D

## **AC OPERATING CONDITIONS**

TEST CONDITIONS(Test Load and Test Input/Output Reference) Input pulse level: 0.2 to Vcc-0.2V Input rising and falling time: 3ns Input and output reference voltage: 0.5 x Vcc Output load: CL=30pF



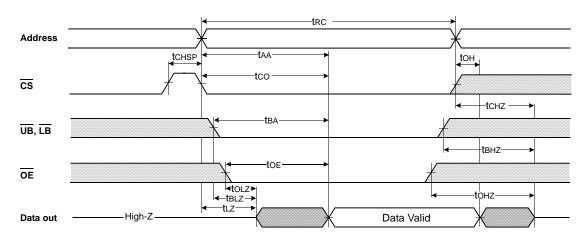
UtRAM

#### Table 16. ASYNCHRONOUS AC CHARACTERISTICS (Vcc=1.7~2.0V, TA=-40 to 85°C)

	Parameter List	Symbol	ę	Speed	Units
	Farameter List	Symbol	Min	Max	Units
	CS High pulse width	<b>t</b> CSHP	10	-	ns
	Read Cycle Time	tRC	70	-	ns
	Page Read Cycle Time	tPC	25	-	ns
	Address Access Time	taa	-	70	ns
	Page Access Time	tPA	-	20	ns
	Chip Select to Output	tco	-	70	ns
Async.	Output Enable to Valid Output	tOE	-	35	ns
(Page)	UB, LB Access Time	tBA	-	35	ns
Read	Chip Select to Low-Z Output	t∟z	10	-	ns
	UB, LB Enable to Low-Z Output	<b>t</b> BLZ	5	-	ns
	Output Enable to Low-Z Output	tolz	5	-	ns
	Chip Disable to High-Z Output	tCHZ	0	12	ns
	UB, LB Disable to High-Z Output	tвнz	0	12	ns
	Output Disable to High-Z Output	tонz	0	12	ns
	Output Hold	toн	3	-	ns
	Write Cycle Time	twc	70	-	ns
	Chip Select to End of Write	tcw	60	-	ns
	ADV Minimum Low Pulse Width	tadv	7	-	ns
	Address Set-up Time to Beginning of Write	tas	0	-	ns
	Address Set-up Time to ADV Falling	tas(a)	0	-	ns
	Address Hold Time from ADV Rising	tah(a)	7	-	ns
Async.	CS Setup Time to ADV Rising	tCSS(A)	10	-	ns
Write	Address Valid to End of Write	taw	60	-	ns
	UB, LB Valid to End of Write	tвw	60	-	ns
	Write Pulse Width	tWP	55 <sup>1)</sup>	-	ns
	WE High Pulse Width	tWHP	5 ns	Latency-1 clock	-
	Write Recovery Time	twr	0	-	ns
	WE Low to Read Latency	twlrl	1	-	clock
	Data to Write Time Overlap	tDW	30	-	ns
	Data Hold from Write Time	tdн	0	_	ns



## ASYNCHRONOUS READ TIMING WAVEFORM



#### Fig.13 TIMING WAVEFORM OF ASYNCHRONOUS READ CYCLE (WE=VIH, WAIT=High-Z)

(ASYNCHRONOUS READ CYCLE)

tCHZ and tOHZ are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
 At any given temperature and voltage condition, tCHZ(Max.) is less than tLZ(Min.) both for a given device and from device to device

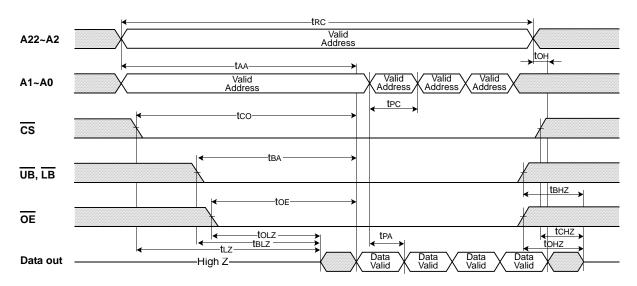
interconnection. 3. In asynchronous read cycle, Clock, ADV and WAIT signals are ignored.

Symbol	Sp	eed	Units	Symbol	Sp	Speed	
Symbol	Min	Мах	Units	Symbol	Min	Max	Units
tRC	70	-	ns	toLz	5	-	ns
taa	-	70	ns	tBLZ	5	-	ns
tco	-	70	ns	tLZ	10	-	ns
tBA	-	35	ns	tснz	0	12	ns
tOE	-	35	ns	tвнz	0	12	ns
tон	3	-	ns	tонz	0	12	ns
<b>t</b> CSHP	10	-	ns				

#### Table 17. ASYNCHRONOUS READ AC CHARACTERISTICS



#### **ASYNCHRONOUS READ TIMING WAVEFORM**



#### Fig.14 TIMING WAVEFORM OF PAGE READ CYCLE(WE=VIH, WAIT=High-Z)

(ASYNCHRONOUS 4 PAGE READ CYCLE)

1. tCHZ and tOHZ are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.

2. At any given temperature and voltage condition, tCHZ(Max.) is less than tLZ(Min.) both for a given device and from device to device interconnection.

3. In asynchronous 4 page read cycle, Clock, ADV and WAIT signals are ignored.

#### Speed Speed Symbol Units Symbol Units Min Max Min Max 70 3 trc ns tон -70 5 -taa ns tolz 5 tPC 25 ns **t**BLZ -20 10 **t**PA \_ ns tlz 70 0 12 tco ns tchz 35 0 12 tва \_ ns tвнz 35 0 12 toe ns tonz

#### Table 18. ASYNCHRONOUS PAGE READ AC CHARACTERISTICS



ns

ns

ns

ns

ns

ns

ns

#### **ASYNCHRONOUS WRITE TIMING WAVEFORM**

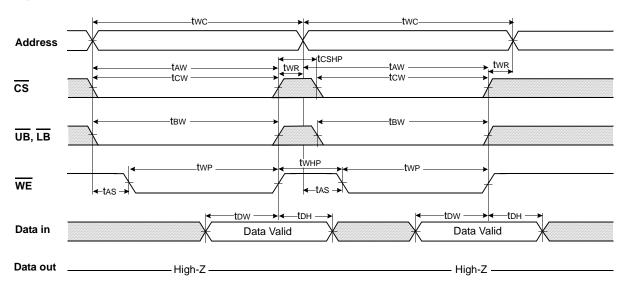


Fig.15 TIMING WAVEFORM OF WRITE CYCLE(1)( DE=VIH, WAIT=High-Z, WE Controlled)

(ASYNCHRONOUS WRITE CYCLE - WE Controlled)

1. A write occurs during the overlap(twp) of low  $\overline{CS}$  and low  $\overline{WE}$ . A write begins when  $\overline{CS}$  goes low and  $\overline{WE}$  goes low with asserting  $\overline{UB}$  or LB for single byte operation or simultaneously asserting UB and LB for double byte operation. A write ends at the earliest transition when CS goes high or WE goes high. The twp is measured from the beginning of write to the end of write.

- 2. two is measured from the CS going low to the end of write. 3. tas is measured from the address valid to the beginning of write.
- 4. twr is measured from the end of write to the address change. twr is applied in case a write ends with CS or WE going high.
- 5. In asynchronous write cycle, Clock, ADV and WAIT signals are ignored.
- 6. Condition for continuous write operation over 50 times : tWP(min)=70ns

#### Table 19. ASYNCHRONOUS WRITE AC CHARACTERISTICS (WE Controlled)

Symbol	Sp	eed	Units	Symbol	Sp	eed	Units
Gymbol	Min	Max	onits	Cymbol	Min	Max	Onto
twc	70	-	ns	tas	0	-	ns
tcw	60	-	ns	twR	0	-	ns
taw	60	-	ns	tDW	30	-	ns
tBW	60	-	ns	tdн	0	-	ns
twp	55 <sup>1)</sup>	-	ns	tCSHP	10	-	ns

1. tWP(min)=70ns for continuous write operation over 50 times.



#### **ASYNCHRONOUS WRITE TIMING WAVEFORM**

Address	twc
cs	
UB, LB	tBW tBW
WE	
Data in	← tDW → ← tDH →     Data Valid
Data out	——————————————————————————————————————

Fig.16 TIMING WAVEFORM OF WRITE CYCLE(2) (DE=VIH, WAIT=High-Z, UB & LB Controlled)

(ASYNCHRONOUS WRITE CYCLE - UB & LB Controlled)

1. A write occurs during the overlap(twP) of low CS and low WE. A write begins when CS goes low and WE goes low with asserting UB or LB for single byte operation or simultaneously asserting UB and LB for double byte operation. A write ends at the earliest transition when  $\overline{CS}$  goes high or  $\overline{WE}$  goes high. The twp is measured from the beginning of write to the end of write. 2. tcw is measured from the  $\overline{CS}$  going low to the end of write.

- 3. tas is measured from the address valid to the beginning of write.
- 4. twr is measured from the end of write to the address change. twr is applied in case a write ends with CS or WE going high.
- 5. In asynchronous write cycle, Clock, ADV and WAIT signals are ignored.

Table 20. ASYNCHRONOUS WRITE AC CHARACTERISTICS (UB & LB Controlled)
--

Symbol	Speed		Units	Symbol	Sp	Units	
Symbol	Min	Max	onito	eynise.	Min	Max	Units
twc	70	-	ns	tas	0	-	ns
tcw	60	-	ns	twR	0	-	ns
tAW	60	-	ns	tDW	30	-	ns
tвw	60	-	ns	tdн	0	-	ns
twp	55 <sup>1)</sup>	-	ns				



#### ASYNCHRONOUS WRITE TIMING WAVEFORM in SYNCHRONOUS MODE

Fig.17 TIMING WAVEFORM OF WRITE CYCLE(Address Latch Type)( DE=VIH, WAIT=High-Z, WE Controlled)

	0 1	2	3 4 5	567	8 9	10 11	12 13	14
CLK								
ADV								
Address	Valid X							
cs	→ tcss	i(A)	tcw —		<b>/</b>			
UB, LB			taw – tBw –		/	/		
WE	tas	tv	/LRL →	twp		1011 N		
Data in					<tdw> ∢ Data Valio</tdw>			
Data out		<ul> <li>Read Late</li> <li>High-Z –</li> </ul>	1 1	•	High	n-Z		

(ADDRESS LATCH TYPE ASYNCHRONOUS WRITE CYCLE - WE Controlled)

1. A write occurs during the overlap(twp) of low  $\overline{CS}$  and low  $\overline{WE}$ . A write begins when  $\overline{CS}$  goes low and  $\overline{WE}$  goes low with asserting  $\overline{UB}$  or LB for single byte operation or simultaneously asserting UB and LB for word operation. A write ends at the earliest transition when  $\overline{CS}$  goes high or  $\overline{WE}$  goes high. The twp is measured from the beginning of write to the end of write.

2. taw is measured from the address valid to the end of write. In this address latch type write timing, two is same as taw.

3. tcw is measured from the  $\overline{CS}$  going low to the end of write.

4. tew is measured from the  $\overline{UB}$  and  $\overline{LB}$  going low to the end of write.

5. Clock input does not have any affect to the write operation if the parameter tWLRL is met.

#### Table 21. ASYNCH. WRITE IN SYNCH. MODE AC CHARACTERISTICS (Address Latch Type, WE Controlled)

Symbol	Speed		Units	Symbol	Spe	Units	
Symbol	Min	Мах	Onito	Symbol	Min	Max	Onits
tadv	7	-	ns	tвw	60	-	ns
tas(a)	0	-	ns	twp	55 <sup>1)</sup>	-	ns
tah(a)	7	-	ns	twlrl	1	-	clock
tCSS(A)	10	-	ns	tas	0	-	ns
tcw	60	-	ns	tDW	30	-	ns
taw	60	-	ns	tdн	0	-	ns



#### ASYNCHRONOUS WRITE TIMING WAVEFORM in SYNCHRONOUS MODE

	0 1 2	3 4 5 0	6 7 8 9 10	11 12 13 14
CLK				
ADV				
Address	Valid X	1		
cs		tcw		
UB, LB		tawtBW		
WE		twp	•	
Data in	Read Later		tow →toH Data Valid	
Data out	High-Z -		High-Z _	

Fig.18 TIMING WAVEFORM OF WRITE CYCLE(Address Latch Type)(OE=VIH, WAIT=High-Z, UB & LB Controlled)

(ADDRESS LATCH TYPE ASYNCHRONOUS WRITE CYCLE - UB & LB Controlled)

- 1. A write occurs during the overlap(twp) of low CS and low WE. A write begins when CS goes low and WE goes low with asserting UB or LB for single byte operation or simultaneously asserting UB and LB for word operation. A write ends at the earliest transition when CS goes or and WE goes high. The twp is measured from the beginning of write to the end of write.
- taw is measured from the address valid to the end of write. In this address latch type write timing, twc is same as taw.
   tcw is measured from the CS going low to the end of write.
   tew is measured from the UB and LB going low to the end of write.

- 5. Clock input does not have any affect to the write operation if the parameter tWLRL is met.

#### Table 22. ASYNCH. WRITE IN SYNCH. MODE AC CHARACTERISTICS (Address Latch Type, UB & LB Controlled)

Symbol	Speed		Units	Symbol	Spe	Units	
Symbol	Min	Max	Onits	eynise.	Min	Max	Units
tadv	7	-	ns	tBW	60	-	ns
tas(a)	0	-	ns	tWP	55 <sup>1)</sup>	-	ns
tAH(A)	7	-	ns	twlrl	1	-	clock
tCSS(A)	10	-	ns	tas	0	-	ns
tcw	60	-	ns	tDW	30	-	ns
taw	60	-	ns	tDH	0	-	ns



#### ASYNCHRONOUS WRITE TIMING WAVEFORM in SYNCHRONOUS MODE

Fig.19 TIMING WAVEFORM OF WRITE CYCLE(Low ADV Type)( DE=VIH, WAIT=High-Z, WE Controlled)

	0 1	2 3	4 5	6 7	8 9	10 11	12	13 14
CLK								
ADV								
Address			twc		, 	*		
cs			-tcw			₩R		
UB, LB			taw tbw					
WE	-tas-	twlrl	twp >					
Data in					tDw →< Data Valid			
		Read Latency 5		/\		/\		
Data out		—— High-Z ——	1			—— High-Z		<u> </u>

(LOW ADV TYPE WRITE CYCLE - WE Controlled)

1. A write occurs during the overlap(twP) of low CS and low WE. A write begins when CS goes low and WE goes low with asserting UB or LB for single byte operation or simultaneously asserting UB and LB for double byte operation. A write ends at the earliest transition when  $\overline{CS}$  goes high or  $\overline{WE}$  goes high. The twp is measured from the beginning of write to the end of write. 2. tcw is measured from the  $\overline{CS}$  going low to the end of write. 3. tas is measured from the address valid to the beginning of write.

4. twr is measured from the end of write to the address change. twr is applied in case a write ends with CS or WE going high.

5. Clock input does not have any affect to the write operation if the parameter tWLRL is met.

#### Table 23. ASYNCH. WRITE IN SYNCH. MODE AC CHARACTERISTICS(Low ADV Type, WE Controlled)

Symbol	Speed		Units	Symbol	Sp	Units	
Symbol	Min	Мах	onits	eybol	Min	Max	Units
twc	70	-	ns	twlrl	1	-	clock
tcw	60	-	ns	tas	0	-	ns
taw	60	-	ns	twr	0	-	ns
tBW	60	-	ns	tDW	30	-	ns
tWP	55 <sup>1)</sup>	-	ns	tdн	0	-	ns



#### ASYNCHRONOUS WRITE TIMING WAVEFORM in SYNCHRONOUS MODE

	0 1	2 3	4 5	6 7	8 9	10 11	12 13	14
CLK								
ADV					Æ			
Address			twc					
cs			-tcw			VR		
UB, LB	←tAS→	twlrl	tBW					
WE			twp					
Data in					w <u> </u>			
Data out		—— High-7				— High-Z —		

Fig.20 TIMING WAVEFORM OF WRITE CYCLE(Low ADV Type)( DE=VIH, WAIT=High-Z, UB & LB Controlled)

(LOW ADV TYPE WRITE CYCLE - UB & LB Controlled)

1. A write occurs during the overlap(twP) of low CS and low WE. A write begins when CS goes low and WE goes low with asserting UB or LB for single byte operation or simultaneously asserting UB and LB for double byte operation. A write ends at the earliest transition when CS goes high or WE goes high. The twP is measured from the beginning of write to the end of write.

2. tcw is measured from the  $\overline{CS}$  going low to the end of write.

3. tas is measured from the address valid to the beginning of write.

4. twe is measured from the end of write to the address change. twe is applied in case a write ends with  $\overline{CS}$  or  $\overline{WE}$  going high.

5. Clock input does not have any affect to the write operation if the parameter tWLRL is met.

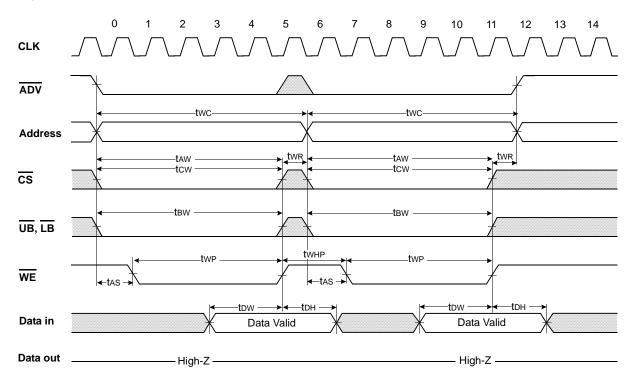
#### Table 24. ASYNCH. WRITE IN SYNCH. MODE AC CHARACTERISTICS(Low ADV Type, UB & LB Controlled)

Symbol	Speed		Units	Symbol	Sp	eed	Units
Symbol	Min	Max	0	eysei	Min	Max	Units
twc	70	-	ns	twlrl	1	-	clock
tcw	60	-	ns	tas	0	-	ns
tAW	60	-	ns	twR	0	-	ns
tBW	60	-	ns	tDW	30	-	ns
twp	55 <sup>1)</sup>	-	ns	tDH	0	-	ns



#### ASYNCHRONOUS WRITE TIMING WAVEFORM in SYNCHRONOUS MODE

Fig.21 TIMING WAVEFORM OF MULTIPLE WRITE CYCLE(Low ADV Type)(OE=VIH, WAIT=High-Z, WE Controlled)



(LOW ADV TYPE MULTIPLE WRITE CYCLE)

1. A write occurs during the overlap(twP) of low  $\overline{CS}$  and low  $\overline{WE}$ . A write begins when  $\overline{CS}$  goes low and  $\overline{WE}$  goes low with asserting  $\overline{UB}$  or LB for single byte operation or simultaneously asserting  $\overline{UB}$  and LB for double byte operation. A write ends at the earliest transition when  $\overline{CS}$  goes high or  $\overline{WE}$  goes high. The twP is measured from the beginning of write to the end of write.

2. tcw is measured from the CS going low to the end of write.

3. tas is measured from the address valid to the beginning of write.

4. twr is measured from the end of write to the address change. twr is applied in case a write ends with CS or WE going high.

5. Clock input does not have any affect to the asynchronous multiple write operation if twHP is shorter than (Read Latency - 1) clock

duration.

6. tWP(min)=70ns for continuous write operation over 50 times.

Symbol	Speed		Units	Symbol		Speed		
Oymbol	Min	Max	onits	eysei	Min	Max	Units	
twc	70	-	ns	twhp	5ns	Latency-1 clock	-	
tcw	60	-	ns	tas	0	-	ns	
taw	60	-	ns	twR	0	-	ns	
tBW	60	-	ns	tDW	30	-	ns	
twp	55 <sup>1)</sup>	-	ns	tDH	0	-	ns	

#### Table 25. ASYNCH. WRITE IN SYNCH. MODE AC CHARACTERISTICS(Low ADV Type Multiple Write, WE Controlled)

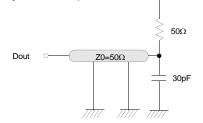


# http://www.BDTIC.com/SAMSUNG *Preliminary* U*t*RAM

Figure 22. AC Output Load Circuit

#### AC OPERATING CONDITIONS

**TEST CONDITIONS**(Test Load and Test Input/Output Reference) Input pulse level: 0.2 to Vcc-0.2V Input rising and falling time: 3ns Input and output reference voltage: 0.5 x Vcc Output load: CL=30pF



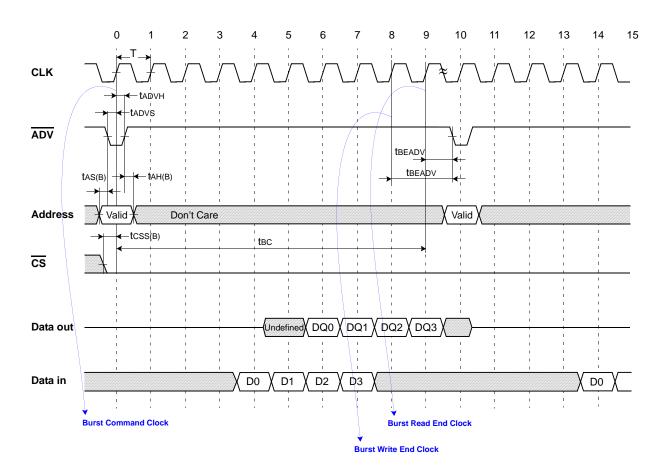
Vtt=0.5 x VDDQ

# Table 26. SYNCHRONOUS AC CHARACTERISTICS (Vcc=1.7~2.0V, TA=-40 to 85°C, Maximum Main Clock Frequency=66MHz)

	Parameter List	Symbol	Sp	eed	Units
	Farameter List	Symbol	Min	Max	Units
	Clock Cycle Time	т	15	200	ns
	Burst Cycle Time	tвс	-	2500	ns
	Address Set-up Time to ADV Falling(Burst)	tas(b)	0	-	ns
	Address Hold Time from ADV Rising(Burst)	tAH(B)	7	-	ns
	ADV Setup Time	tadvs	5	-	ns
Burst Operation (Common)	ADV Hold Time	<b>t</b> advh	7	-	ns
	CS Setup Time to Clock Rising(Burst)	tCSS(B)	5	-	ns
	Burst End to New ADV Falling	<b>t</b> BEADV	7	-	ns
	Burst Stop to New ADV Falling	<b>t</b> BSADV	12	-	ns
	CS Low Hold Time from Clock	<b>t</b> CSLH	7	-	ns
	CS High Pulse Width	<b>t</b> CSHP	5	-	ns
	ADV High Pulse Width	<b>t</b> ADHP	5	-	ns
	Chip Select to WAIT Low	tw∟	-	10	ns
	ADV Falling to WAIT Low	tawl	-	10	ns
	Clock to WAIT High	twн	-	12	ns
	Chip De-select to WAIT High-Z	twz	-	12	ns
	UB, LB Enable to End of Latency Clock	tBEL	1	-	Clock
	Output Enable to End of Latency Clock	<b>t</b> OEL	1	-	Clock
	UB, LB Valid to Low-Z Output	tBLZ	5	-	ns
	Output Enable to Low-Z Output	toLz	5	-	ns
Burst Read	Latency Clock Rising Edge to Data Output	tCD	-	10	ns
Operation	Output Hold	tон	3	-	ns
	Burst End Clock to Output High-Z	tHZ	-	12	ns
	Chip De-select to Output High-Z	tCHZ	-	12	ns
	Output Disable to Output High-Z	tонz	-	12	ns
	UB, LB Disable to Output High-Z	tвнz	-	12	ns
	WE Set-up Time to Command Clock	twes	5	-	ns
	WE Hold Time from Command Clock	tWEH	5	-	ns
	WE High Pulse Width	twhp	5	-	ns
Burst Write	UB, LB Set-up Time to Clock	tBS	5	-	ns
Operation	UB, LB Hold Time from Clock	tвн	5	-	ns
•	Byte Masking Set-up Time to Clock	tBMS	7	-	ns
	Byte Masking Hold Time from Clock	tвмн	7	-	ns
	Data Set-up Time to Clock	tDS	5	-	ns
	Data Hold Time from Clock	<b>t</b> DHC	3	-	ns



#### SYNCHRONOUS BURST OPERATION TIMING WAVEFORM



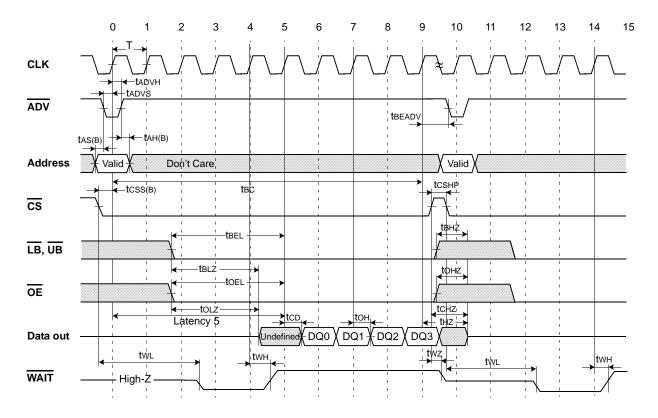
#### Fig.23 TIMING WAVEFORM OF BASIC BURST OPERATION [Latency=5,Burst Length=4]

Symbol	Speed		Units	Symbol	Sp	Units	
Symbol	Min	Мах	Units	Cymbol	Min	Max	Units
т	15	200	ns	tas(b)	0	-	ns
tBC	-	2500	ns	tah(b)	7	-	ns
tadvs	5	-	ns	tCSS(B)	5	-	ns
<b>t</b> advh	7	-	ns	<b>t</b> BEADV	7	-	ns



#### SYNCHRONOUS BURST READ TIMING WAVEFORM

#### Fig.24 TIMING WAVEFORM OF BURST READ CYCLE(1) [Latency=5,Burst Length=4,WP=Low enable](WE=VIH) - CS Toggling Consecutive Burst Read



(SYNCHRONOUS BURST READ CYCLE - CS Toggling Consecutive Burst Read)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

- 2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)
  - /WAIT High(tWH) : Data available(driven by Latency-1 clock)

WAIT High-Z(tWZ): Data don't care(driven by CS high going edge)
 Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

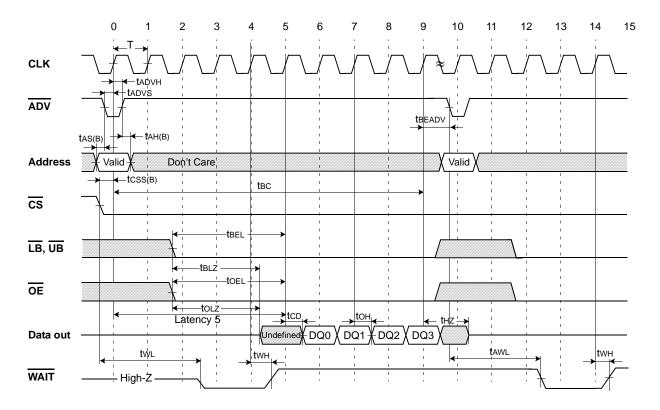
Symbol	Sp	Speed		Symbol	Sp	eed	Units
Cymbol	Min	Max	Units	Cymbol	Min	Max	Onits
tCSHP	5	-	ns	tонz	-	12	ns
tBEL	1	-	clock	tвнz	-	12	ns
toel	1	-	clock	tCD	-	10	ns
tBLZ	5	-	ns	toн	3	-	ns
toLz	5	-	ns	tw∟	-	10	ns
tHZ	-	12	ns	twн	-	12	ns
tснz	-	12	ns	twz	-	12	ns

#### Table 28. BURST READ AC CHARACTERISTICS (CS Toggling Consecutive Burst)



#### SYNCHRONOUS BURST READ TIMING WAVEFORM

#### Fig.25 TIMING WAVEFORM OF BURST READ CYCLE(2) [Latency=5,Burst Length=4,WP=Low enable](WE=VIH) - CS Low Holding Consecutive Burst Read



(SYNCHRONOUS BURST READ CYCLE - CS Low Holding Consecutive Burst Read)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)

/WAIT High(tWH) : Data available(driven by Latency-1 clock)

/WAIT High(tWH): Data available(driven by Latency-1 clock)
/WAIT High-Z(tWZ): Data don't care(driven by CS high going edge)
3. Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.
4. The consecutive multiple burst read operation with holding CS low is possible through issuing only new ADV and address.
5. Burst Cycle Time(tBC) should not be over 2.5µs.

#### Table 29. BURST READ AC CHARACTERISTICS (CS Low Holding Consecutive Burst)

Symbol	Speed		Units	Symbol	Spe	eed	Units
Cymbol	Min	Мах	Units	Cymbol	Min	Мах	onita
tBEL	1	-	clock	tCD	-	10	ns
tOEL	1	-	clock	toн	3	-	ns
tBLZ	5	-	ns	tw∟	-	10	ns
toLZ	5	-	ns	tAWL	-	10	ns
tHZ	-	12	ns	twн	_	12	ns

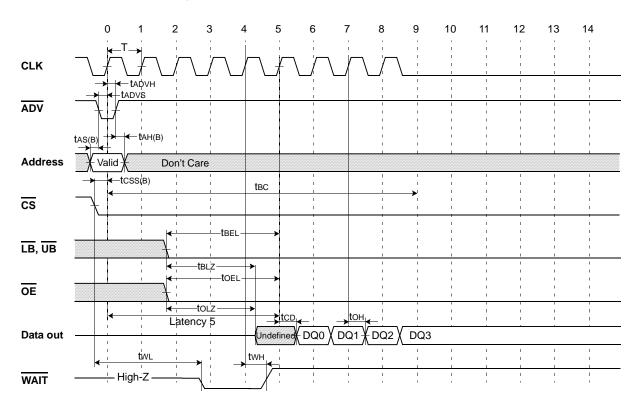


Preliminary

UtRAM

#### SYNCHRONOUS BURST READ TIMING WAVEFORM

# Fig.26 TIMING WAVEFORM OF BURST READ CYCLE(3) [Latency=5,Burst Length=4,WP=Low enable](WE=VIH) - Last Data Sustaining



(SYNCHRONOUS BURST READ CYCLE - Last Data Sustaining)

1. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)

/WAIT High(tWH) : Data available(driven by Latency-1 clock)

/WAIT High-Z(tWZ) : Data don't care(driven by CS high going edge)

2. Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

3. Burst Cycle Time(tBC) should not be over 2.5µs.

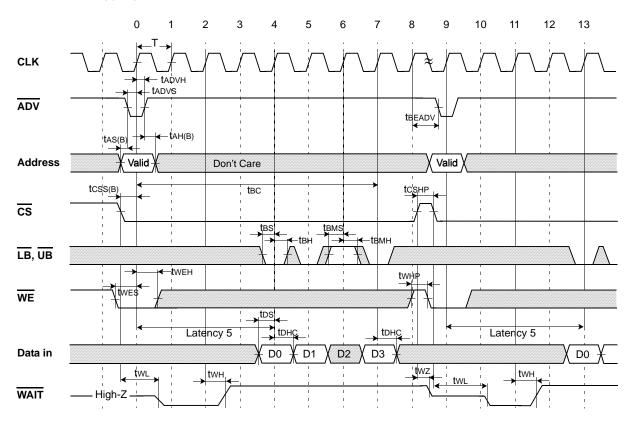
#### Table 30. BURST READ AC CHARACTERISTICS(Last Data Sustaining)

Symbol	Speed		Units	Symbol	Spe	eed	Units
Symbol	Min	Max	Units	Cymbol	Min	Max	Onits
tBEL	1	-	clock	tCD	-	10	ns
tOEL	1	-	clock	tон	3	-	ns
tBLZ	5	-	ns	twL	-	10	ns
toLz	5	-	ns	twн	_	12	ns



#### SYNCHRONOUS BURST WRITE TIMING WAVEFORM

#### Fig.27 TIMING WAVEFORM OF BURST WRITE CYCLE(1) [Latency=5,Burst Length=4,WP=Low enable](OE=VIH) - CS Toggling Consecutive Burst Write



(SYNCHRONOUS BURST WRITE CYCLE - CS Toggling Consecutive Burst Write)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.
 /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)

- /WAIT High(tWH) : Data available(driven by Latency-1 clock)
- /WAIT High-Z(tWZ) : Data don't care(driven by CS high going edge)

4. D2 is masked by UB and LB.

5. Burst Cycle Time(tBC) should not be over 2.5µs.

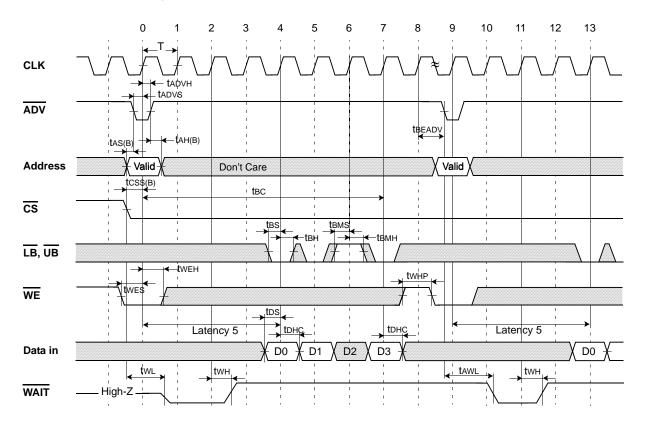
Symbol	Speed		Units	Symbol	Speed		Units
Cymbol	Min	Max	onits	Cymbol	Min	Мах	Onits
<b>t</b> CSHP	5	-	ns	twhp	5	-	ns
tBS	5	-	ns	tDS	5	-	ns
tвн	5	-	ns	<b>t</b> DHC	3	-	ns
tBMS	7	-	ns	tw∟	-	10	ns
tвмн	7	-	ns	twн	-	12	ns
twes	5	-	ns	twz	-	12	ns
tweн	5	-	ns				

#### Table 31. BURST WRITE AC CHARACTERISTICS(CS Toggling Consecutive Burst)



#### SYNCHRONOUS BURST WRITE TIMING WAVEFORM

# Fig.28 TIMING WAVEFORM OF BURST WRITE CYCLE(2) [Latency=5,Burst Length=4,WP=Low enable]( $\overline{OE}=V_{H}$ ) - CS Low Holding Consecutive Burst Write



(SYNCHRONOUS BURST WRITE CYCLE - CS Low Holding Consecutive Burst Write)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV

should be met.

2. Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

3. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)

/WAIT High(tWH) : Data available(driven by Latency-1 clock)

/WAIT High-Z(tWZ) : Data don't care(driven by CS high going edge) 4. D2 is masked by UB and LB.

The consecutive multiple burst read operation with holding CS low is possible through issuing only new ADV and address.

6. Burst Cycle Time(tBC) should not be over 2.5μs.

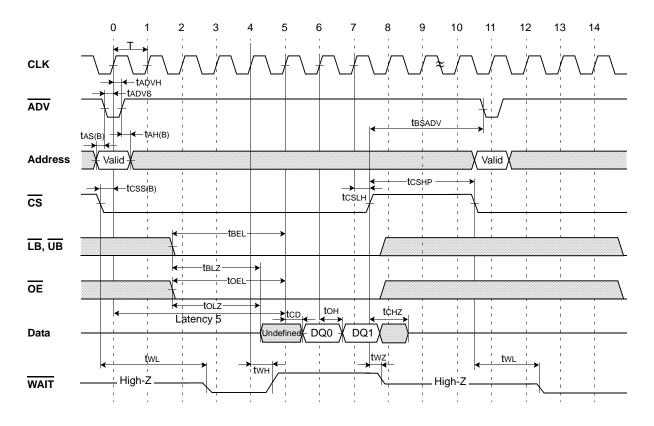
Table 32. B	URST WRITE AC CHARACTE	ERISTIC	S(CS Low Holding C	onsecutive Burst)	
Symbol	Speed	Units	Symbol	Spe	ed

Symbol	Sp	beed	Units	Symbol	Spe	eed	Units
Cymbol	Min	Max	onits	Cymbol	Min	Max	onita
tBS	5	-	ns	twhp	5	-	ns
tвн	5	-	ns	tDS	5	-	ns
tBMS	7	-	ns	<b>t</b> DHC	3	-	ns
tвмн	7	-	ns	twL	-	10	ns
twes	5	-	ns	tawl	-	10	ns
tWEH	5	-	ns	twн	-	12	ns



#### SYNCHRONOUS BURST READ STOP TIMING WAVEFORM

#### Fig.29 TIMING WAVEFORM OF BURST READ STOP by CS [Latency=5,Burst Length=4,WP=Low enable](WE=VIH)



(SYNCHRONOUS BURST READ STOP TIMING)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBSADV

should be met WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)
 WAIT High(tWH) : Data available(driven by Latency-1 clock)
 WAIT High-Z(tWZ) : Data don't care(driven by CS high going edge)
 Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.
 The burst operation experime build not be paraetal for any 2.5 for the start 2.5 for the first clock rising.

4. The burst stop operation should not be repeated for over  $2.5 \mu s$ .

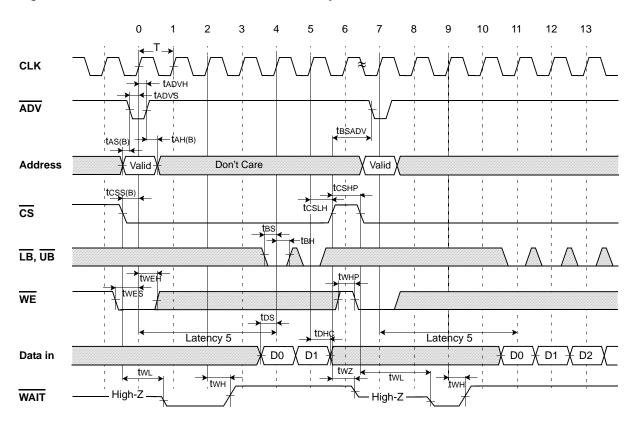
#### Table 33. BURST READ STOP AC CHARACTERISTICS

Symbol	Sp	Speed		Symbol	Speed		Units
Cymbol	Min	Max	Units	Cymbol	Min	Max	onito
tBSADV	12	-	ns	tCD	-	10	ns
<b>t</b> CSLH	7	-	ns	toн	3	-	ns
tCSHP	5	-	ns	tснz	-	12	ns
tBEL	1	-	clock	twL	-	10	ns
tOEL	1	-	clock	twн	-	12	ns
tBLZ	5	-	ns	twz	-	12	ns
toLz	5	-	ns				



#### SYNCHRONOUS BURST WRITE STOP TIMING WAVEFORM

Fig.30 TIMING WAVEFORM OF BURST WRITE STOP by CS [Latency=5,Burst Length=4,WP=Low enable](OE=VIH)



(SYNCHRONOUS BURST WRITE STOP TIMING)

1. The new burst operation can be issued only after the previous burst operation is finished.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)

/WAIT High(tWH) : Data available(driven by Latency-1 clock)

WAIT High-Z(tWZ): Data don't care(driven by CS high going edge)
 Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. The burst stop operation should not be repeated for over 2.5µs.

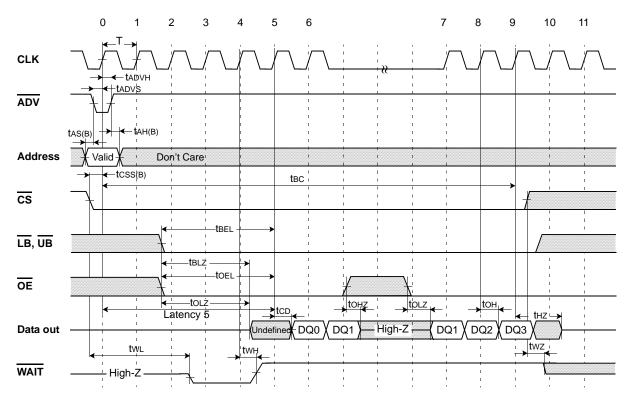
#### Table 34. BURST WRITE STOP AC CHARACTERISTICS

Symbol	Speed		Units	Symbol	Sp	eed	Units
Cymbol	Min	Мах	onits	Cymbol	Min	Max	Onits
<b>t</b> BSADV	12	-	ns	twhp	5	-	ns
tcslh	7	-	ns	tDS	5	-	ns
<b>t</b> CSHP	5	-	ns	<b>t</b> DHC	3	-	ns
tBS	5	-	ns	twL	-	10	ns
tвн	5	-	ns	twн	-	12	ns
twes	5	-	ns	twz	-	12	ns
tweн	5	-	ns				



#### SYNCHRONOUS BURST READ SUSPEND TIMING WAVEFORM

Fig.31 TIMING WAVEFORM OF BURST READ SUSPEND CYCLE(1) [Latency=5,Burst Length=4,WP=Low enable](WE=VH)



(SYNCHRONOUS BURST READ SUSPEND CYCLE)

1. If clock input is halted during burst read operation, the data out will be suspended. During the burst read suspend period, OE high

drives data out to high-Z. If clock input is resumed, the suspended data will be out first. 2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge)

/WAIT High(tWH) : Data available(driven by Latency-1 clock)

WAIT High-Z(tWZ): Data don't careful for by Calibratic products of the product of t

Build States low during suspend period, the previous data will be sustained.
 Burst Cycle Time(tBC) should not be over 2.5µs.

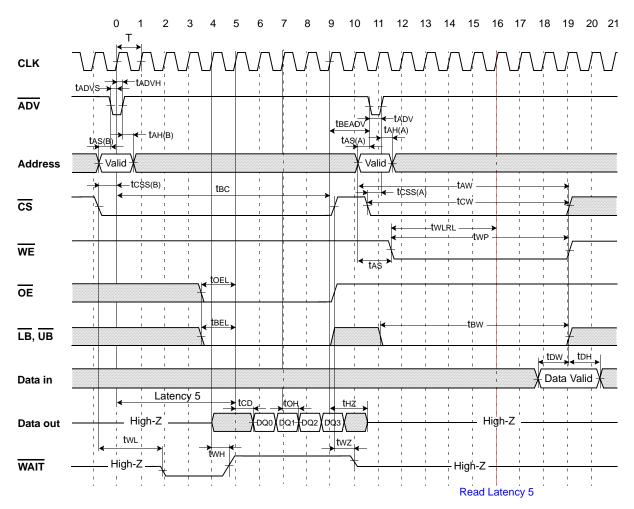
#### Table 35. BURST READ SUSPEND AC CHARACTERISTICS

Symbol	Sp	Speed		Symbol	Sp	eed	Units
Symbol	Min	Мах	Units	Cymbol	Min	Max	Units
tBEL	1	-	clock	tHZ	-	12	ns
tOEL	1	-	clock	tонz	-	12	ns
tBLZ	5	-	ns	tw∟	-	10	ns
to∟z	5	-	ns	twн	-	12	ns
tCD	-	10	ns	twz	-	12	ns
toн	3	-	ns				



#### TRANSITION TIMING WAVEFORM BETWEEN READ AND WRITE

#### Fig.32 SYNCH. BURST READ to ASYNCH. WRITE(Address Latch Type) TIMING WAVEFORM [Latency=5, Burst Length=4]



(SYNCHRONOUS BURST READ CYCLE)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge) /WAIT High(tWH) : Data available(driven by Latency-1 clock)

WAIT High-Z(WZ): Data don't care(driven by CS high going edge)
 Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

(ADDRESS LATCH TYPE ASYNCHRONOUS WRITE CYCLE - WE controlled)

1. Clock input does not have any affect to the write operation if WE is driven to low before Read Latency-1 clock. Read Latency-1 clock in write timing is just a reference to WE low going for proper write operation.

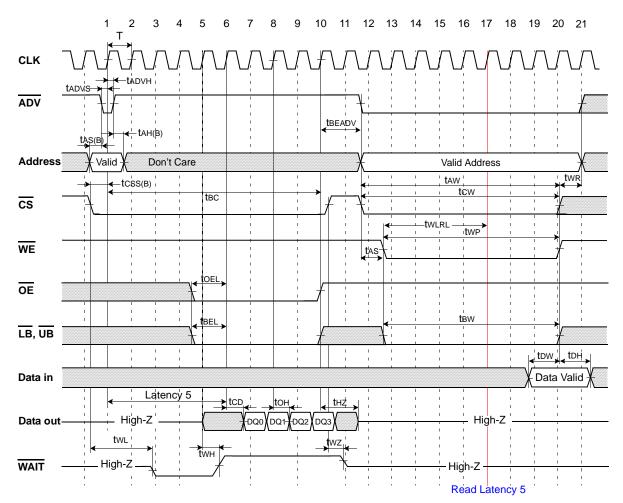
#### Table 36. BURST READ to ASYNCH. WRITE(Address Latch Type) AC CHARACTERISTICS

Symbol	Sp	eed	Unite	Units Symbol –	Speed		Units
Symbol	Min	Мах	Units		Min	Max	Units
<b>t</b> BEADV	7	-	ns	tWLRL	1	-	clock



#### TRANSITION TIMING WAVEFORM BETWEEN READ AND WRITE

#### Fig.33 SYNCH. BURST READ to ASYNCH. WRITE(Low ADV Type) TIMING WAVEFORM [Latency=5, Burst Length=4]



(SYNCHRONOUS BURST READ CYCLE)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge) /WAIT High(tWH) : Data available(driven by Latency-1 clock)

WAIT High-Z(tWZ): Data don't care(driven by CS high going edge)
 Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

(LOW ADV TYPE ASYNCHRONOUS WRITE CYCLE - WE controlled)

1. Clock input does not have any affect to the write operation if WE is driven to low before Read Latency-1 clock. Read Latency-1 clock in write timing is just a reference to WE low going for proper write operation.

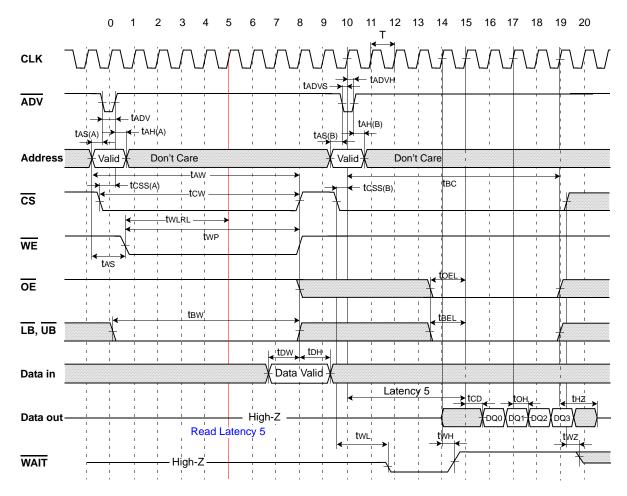
#### Table 37. BURST READ to ASYNCH. WRITE(Low ADV Type) AC CHARACTERISTICS

Symbol	Sp	eed	Unite	Units Symbol	Sp	Units	
Symbol	Min	Max		Min	Max	Units	
<b>t</b> BEADV	7	-	ns	twlrl	1	-	clock



#### TRANSITION TIMING WAVEFORM BETWEEN READ AND WRITE

#### Fig.34 ASYNCH. WRITE(Address Latch Type) to SYNCH. BURST READ TIMING WAVEFORM [Latency=5, Burst Length=4]



(SYNCHRONOUS BURST READ CYCLE)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge) /WAIT High(tWH) : Data available(driven by Latency-1 clock)

WAIT High-Z(tWZ) : Data don't care(driven by CS high going edge) 3. Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

(ADDRESS LATCH TYPE ASYNCHRONOUS WRITE CYCLE - WE controlled)

1. Clock input does not have any affect to the write operation if WE is driven to low before Read Latency-1 clock. Read Latency-1 clock in write timing is just a reference to WE low going for proper write operation.

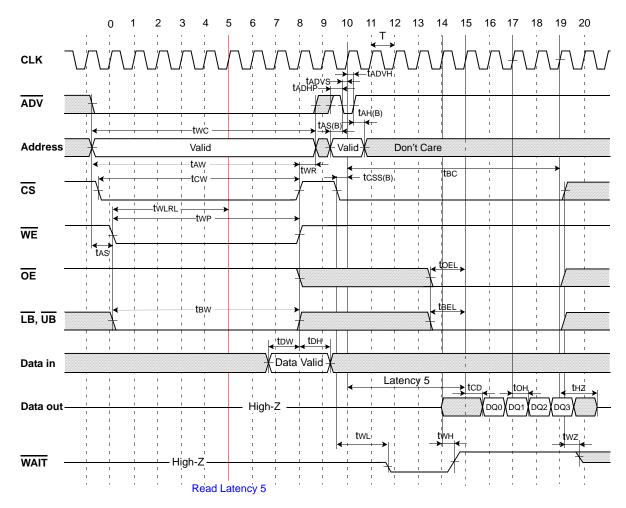
#### Table 38. ASYNCH. WRITE(Address Latch Type) to BURST READ AC CHARACTERISTICS

Symbol	Speed		Units	Symbol	Speed		Units
	Min	Max	Units	Symbol	Min	Max	Units
twLRL	1	-	clock				



#### TRANSITION TIMING WAVEFORM BETWEEN READ AND WRITE

#### Fig.35 ASYNCH. WRITE(Low ADV Type) to SYNCH. BURST READ TIMING WAVEFORM [Latency=5, Burst Length=4]



(SYNCHRONOUS BURST READ CYCLE)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge) (WAIT High(tWH): Data available(driven by Latency-1 clock)
 (WAIT High(tWH): Data available(driven by Latency-1 clock)
 (WAIT High-Z(tWZ): Data don't care(driven by <u>CS</u> high going edge)
 Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

(LOW ADV TYPE ASYNCHRONOUS WRITE CYCLE - WE controlled)

1. Clock input does not have any affect to the write operation if WE is driven to low before Read Latency-1 clock. Read Latency-1 clock in write timing is just a reference to WE low going for proper write operation.

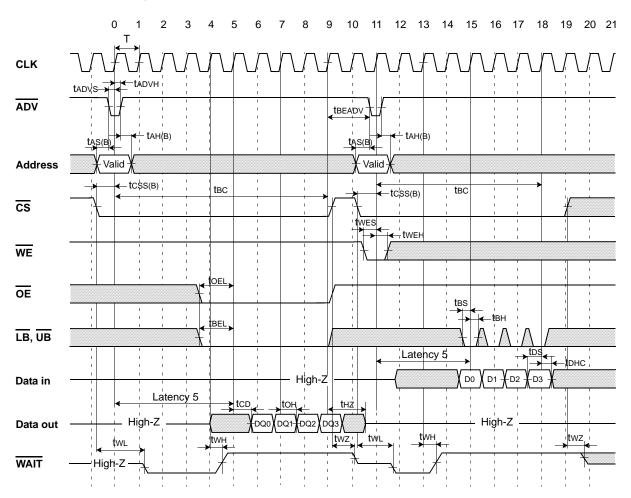
#### Table 39. ASYNCH. WRITE(Low ADV Type) to BURST READ AC CHARACTERISTICS

Symbol	Speed		Units	Symbol	Speed		Units
Symbol	Min	Мах	Units	Cymbol	Min	Max	Onits
twlrl	1	-	clock	<b>t</b> ADHP	5	-	ns



#### TRANSITION TIMING WAVEFORM BETWEEN READ AND WRITE

#### Fig.36 SYNCH. BURST READ to SYNCH. BURST WRITE TIMING WAVEFORM [Latency=5, Burst Length=4]



(SYNCHRONOUS BURST READ & WRITE CYCLE)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

2. /WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge) /WAIT High(tWH) : Data available(driven by Latency-1 clock)

/WAIT High-Z(tWZ) : Data don't care(driven by CS high going edge)

3. Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

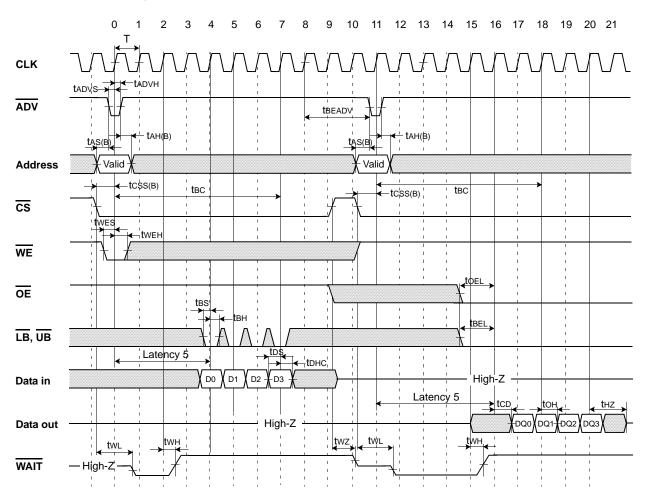
#### Table 40. BURST READ to BURST WRITE AC CHARACTERISTICS

Symbol	Sp	Speed		Symbol	Speed		Units
Symbol	Min	Max	Units	Cymbol	Min	Max	onna
<b>t</b> BEADV	7	-	ns				



#### TRANSITION TIMING WAVEFORM BETWEEN READ AND WRITE

# Fig.37 SYNCH. BURST WRITE to SYNCH. BURST READ TIMING WAVEFORM [Latency=5, Burst Length=4]



(SYNCHRONOUS BURST READ & WRITE CYCLE)

1. The new burst operation can be issued only after the previous burst operation is finished. For the new burst operation, tBEADV should be met.

 WAIT Low(tWL or tAWL) : Data not available(driven by CS low going edge or ADV low going edge) /WAIT High(tWH) : Data available(driven by Latency-1 clock)

/WAIT High-Z(tWZ) : Data don't care(driven by  $\overline{CS}$  high going edge)

3. Multiple clock risings are allowed during low ADV period. The burst operation starts from the first clock rising.

4. Burst Cycle Time(tBC) should not be over 2.5µs.

#### Table 41. BURST WRITE to BURST READ AC CHARACTERISTICS

Symbol	Sp	Speed		Symbol	Speed		Units
Symbol	Min	Max	Units	Cymbol	Min	Max	onna
<b>t</b> BEADV	7	-	ns				



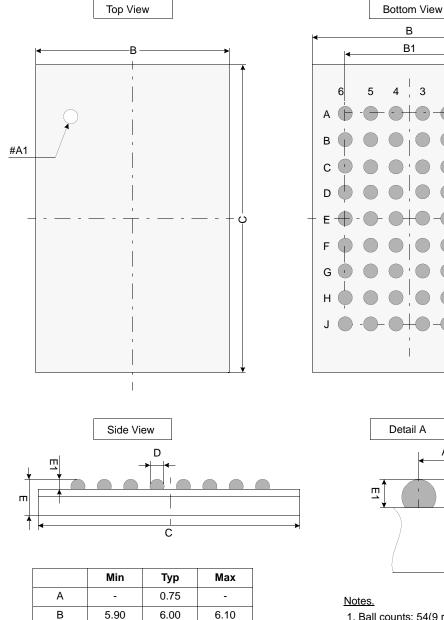
Unit: millimeters

υG

UtRAM

#### PACKAGE DIMENSION

54 BALL FINE PITCH BALL GRID ARRAY(0.75mm ball pitch)



3.75

8.00

6.00

0.45

-

-

-

-

7.90

-

0.40

-

0.25

-

-

8.10

-

0.50

1.00

-

0.10

Detail	A	]		
	<u>А</u>	`	$\Box$	
		ſ		Y
(				

http://www.BDTIC.com/SAMSUNG Preliminary

2

- 1. Ball counts: 54(9 row x 6 column)
- 2. Ball pitch: (x,y)=(0.75 x 0.75)(typ.)
- 3. All tolerence are  $\pm 0.050$  unless specified beside figure.
- 4. Typ: Typical
- 5. Y is coplanarity



B1

С

C1

D

Е

E1

Υ